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DIALOG(R) File 352: Derwent WPI
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Lapping powder composition - has water, alumina, boehmite, polyamine group chelate compound and/or polyamino carboxylic acid group chelate compound

Patent Assignee: FUJIMI INC KK (FUJI-N)

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 11092749	A	19990406	JP 9152750	A	19910318	199928 B
			JP 98212534	A	19910318	
JP 3055060	B2	20000619	JP 9152750	A	19910318	200033
			JP 98212534	A	19910318	

Priority Applications (No Type Date): JP 90227580 A 19900829

Patent Details:

Patent No	Kind	Ln	Pg	Main IPC	Filing Notes
JP 11092749	A	4		C09K-003/14	Div ex application JP 9152750
JP 3055060	B2	4		C09K-003/14	Div ex application JP 9152750
					Previous Publ. patent JP 11092749

Abstract (Basic): JP 11092749 A

NOVELTY - The Tapping powder composition comprises water, alumina and a chelate compound. The composition further includes boehmite or an aluminium salt, and the chelate includes disodium ethylene diamine tetra-acetate. The aluminium salt includes aluminum sulphate.

USE - For precision polishing silicon and compound semiconductor substrate, magnetic memory hard disc and laser device.

ADVANTAGE - High abrasive speed without surface problems such as scratches, pits and cracks on polished surface can be achieved by the material.

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Derwent Class: E19; G04; L02; L03; P61; U11

International Patent Class (Main): C09K-003/14

International Patent Class (Additional): B24B-037/00